

Tack Flux No-Clean for Low Temp in Jar 75g

Product Highlights

Ideal for all rework, solder, de-solder and reflow applications
 Non-corrosive, non-conductive, no-clean
 Tack flux will not run all over PCB when applied
 Has a pleasant odor
 Excellent wetting
 Easily cleaned with isopropyl alcohol (IPA)
 Attachment of BGA spheres
 Soldering flip chip components
 Long stencil life
 Wide process window
 Clear residue
 Commonly used with Sn42/Bi58, Sn42/Bi57.6/Ag0.4,
 and Sn42/Bi57/Ag1 alloys, which melt at 138°C (281°F)
RoHS 3 and REACH compliant



Specifications

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| Flux Type: | Synthetic No-Clean (for low temperature applications) |
| Flux Classification: | RELO |
| Flux Activation Temperature: | 100°C (212°F) |
| Color: | Light yellow to orange/brown |
| Packaging: | Jar 75g |
| Shelf Life: | Refrigerated >24 months, Unrefrigerated >24 months |

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F)
 >4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Do not freeze. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Conforms to the following Industry Standards:

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| J-STD-004B, Amendment 1 (Solder Fluxes): | Yes |
| RoHS 3 Directive (EU) 2015/863: | Yes |